

**Product Texts**

Rapidly freezing UV stabilized general-purpose injection molding grade.

Abbreviated designation according to ISO 1043-1: POM

Designation according to ISO 29988-POM-K,,M-GLR,3-2

Processing/Physical Characteristics	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melt volume-flow rate, MVR	7.5	cm <sup>3</sup> /10min	ISO 1133
Temperature	190	°C	-
Load	2.16	kg	-
<sup>[C]</sup> Molding shrinkage, parallel	2.2	%	ISO 294-4, 2577
<sup>[C]</sup> Molding shrinkage, normal	1.9	%	ISO 294-4, 2577
<sup>[C]</sup> Ejection temperature	110	°C	-

[C]: CAMPUS

Mechanical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Tensile Modulus	2600	MPa	ISO 527
<sup>[C]</sup> Yield stress	63	MPa	ISO 527
<sup>[C]</sup> Yield strain	10.5	%	ISO 527
<sup>[C]</sup> Nominal strain at break	27	%	ISO 527
<sup>[C]</sup> Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
<sup>[C]</sup> Charpy impact strength, +23°C	280	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy impact strength, -30°C	250	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy notched impact strength, +23°C	6.5	kJ/m <sup>2</sup>	ISO 179/1eA
<sup>[C]</sup> Charpy notched impact strength, -30°C	6	kJ/m <sup>2</sup>	ISO 179/1eA

[C]: CAMPUS

Thermal properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
<sup>[C]</sup> Temp. of deflection under load, 1.80 MPa	90	°C	ISO 75-1/-2
<sup>[C]</sup> Temp. of deflection under load, 0.45 MPa	154	°C	ISO 75-1/-2
<sup>[C]</sup> Coeff. of linear therm. expansion, parallel	110	E-6/K	ISO 11359-1/-2
<sup>[C]</sup> Burning Behav. at 1.5 mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.6	mm	-
Yellow Card available	yes	-	-
<sup>[C]</sup> Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Yellow Card available	yes	-	-

[C]: CAMPUS

Electrical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Relative permittivity, 100Hz	3.8	-	IEC 62631-2-1
<sup>[C]</sup> Relative permittivity, 1MHz	3.8	-	IEC 62631-2-1
<sup>[C]</sup> Dissipation factor, 100Hz	10	E-4	IEC 62631-2-1
<sup>[C]</sup> Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
<sup>[C]</sup> Volume resistivity	1E11	Ohm*m	IEC 62631-3-1
<sup>[C]</sup> Surface resistivity	1E13	Ohm	IEC 62631-3-2
<sup>[C]</sup> Electric strength	85	kV/mm	IEC 60243-1
<sup>[C]</sup> Comparative tracking index	600	-	IEC 60112

[C]: CAMPUS

Other properties	Value	Unit	Test Standard
<sup>[C]</sup> Water absorption	0.8	%	Sim. to ISO 62
<sup>[C]</sup> Humidity absorption	0.2	%	Sim. to ISO 62
<sup>[C]</sup> Density	1410	kg/m <sup>3</sup>	ISO 1183

[C]: CAMPUS

**Ultraform® N2320 U03 AT UN**

POM

BASF

Test specimen production	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Injection Molding, melt temperature	200	°C	ISO 294
Injection Molding, mold temperature	90	°C	ISO 294
Injection Molding, injection velocity	200	mm/s	ISO 294

[C]: CAMPUS

Processing Recommendation Injection Molding	Value	Unit	Test Standard
Pre-drying - Temperature	100	°C	-
Pre-drying - Time	3	h	-
Processing humidity	≤0.2	%	-
Melt temperature	190 - 230	°C	-
Mold temperature	60 - 120	°C	-

**Characteristics****Processing**

Injection Molding

**Special Characteristics**

U.V. stabilized or stable to weather

**Delivery form**

Pellets

**Applications**

General Purpose

**Additives**

Release agent

**Regional Availability**

North America

**Other text information****Injection molding**

## PREPROCESSING

Pre/Post-processing, max. allowed water content: .2 %

Pre/Post-processing, Pre-drying, Temperature: 100 °C

Pre/Post-processing, Pre-drying, Time: 3 h

## PROCESSING

injection molding, Melt temperature, range: 190 - 230 °C

injection molding, Melt temperature, recommended: 200 °C

injection molding, Mold temperature, range: 60 - 120 °C

injection molding, Mold temperature, recommended: 90 °C

injection molding, Dwell time, thermoplastics: 10 min